

ABSTRACT OF THE DISCLOSURE

A heat sink is fastened to an annular portion of a substrate of an integrated circuit module on a printed circuit card by means of a cured layer of cure shrinkable adhesive. A circuit chip is soldered to a central portion of the substrate, around which the annular portion extends. A layer of thermally conductive material is placed between the circuit chip and a central portion of the heat sink, to be compressed as the layer of cure shrinkable adhesive is cured. A compression limiting structure may additionally extend between the heat sink and the annular portion of the substrate, limiting the shrinkage of the adhesive and thus the compression of the thermally conductive material and the flexure of the substrate.